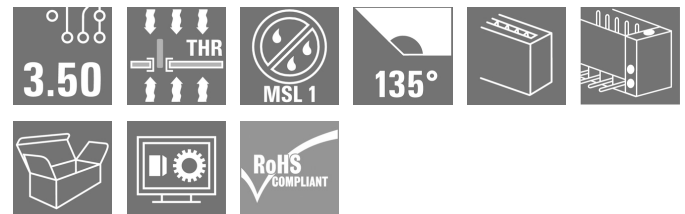


SL-SMT 3.50/17/135F 3.2SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Product image**

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

Version	PCB plug-in connector, male header, Flange, THT/THR solder connection, 3.50 mm, Number of poles: 17, 135°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1003670000
Type	SL-SMT 3.50/17/135F 3.2SN BK BX
GTIN (EAN)	4032248700295
Qty.	24 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Box

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Technical data**Dimensions and weights**

Depth	13.2 mm	Depth (inches)	0.52 inch
Height	16.2 mm	Height (inches)	0.638 inch
Height of lowest version	13 mm	Width	66.5 mm
Width (inches)	2.618 inch	Net weight	5.58 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50		
Type of connection	Board connection		
Mounting onto the PCB	THT/THR solder connection		
Pitch in mm (P)	3.5 mm		
Pitch in inches (P)	0.138 "		
Outgoing elbow	135°		
Number of poles	17		
Number of solder pins per pole	1		
Solder pin length (l)	3.2 mm		
Solder pin dimensions	d = 1.2 mm, Octagonal		
Solder eyelet hole diameter (D)	1.3 mm		
Solder eyelet hole diameter tolerance (D)+	0,1 mm		
Outside diameter of solder pad	2.3 mm		
Template aperture diameter	2.1 mm		
L1 in mm	56 mm		
L1 in inches	2.205 "		
Number of rows	1		
Pin series quantity	1		
Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back-of-hand-safe unplugged		
Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged		
Protection degree	IP10		
Volume resistance	≤5 mΩ		
Plugging cycles	25		
Plugging force/pole, max.	10 N		
Pulling force/pole, max.	8 N		
Tightening torque	Torque type	Mounting screw, PCB	
	Usage information	Tightening torque	min. 0.1 Nm
			max. 0.15 Nm
		Recommended screw	Part number PTSC KA 2.2X4.5 WN1412

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	tinned	Layer structure of solder connection	2...4 µm Ni / 5...8 µm Sn glossy
Layer structure of plug contact	2...4 µm Ni / 5...8 µm Sn glossy	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

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Technical data**Rated data acc. to IEC**

tested acc. to standard

IEC 60664-1, IEC 61984

Rated current, max. number of poles
(Tu=20°C)

12 A

Rated current, max. number of poles
(Tu=40°C)

10 A

Rated voltage for surge voltage class /
pollution degree III/2

160 V

Rated impulse voltage for surge voltage
class/ pollution degree II/2

2.5 kV

Rated impulse voltage for surge voltage
class/ contamination degree III/3

2.5 kV

Rated current, min. number of poles
(Tu=20°C)

15 A

Rated current, min. number of poles
(Tu=40°C)

13 A

Rated voltage for surge voltage class /
pollution degree II/2

320 V

Rated voltage for surge voltage class /
pollution degree III/3

160 V

Rated impulse voltage for surge voltage
class/ pollution degree III/2

2.5 kV

Rated data acc. to CSA

Rated voltage (Use group B / CSA)

300 V

Rated current (Use group B / CSA)

10 A

Rated voltage (Use group D / CSA)

300 V

Rated current (Use group D / CSA)

10 A

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059)

300 V

Rated current (Use group B / UL 1059)

10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Rated voltage (Use group D / UL 1059)

300 V

Rated current (Use group D / UL 1059)

10 A

Packing

Packaging

Box

VPE length

338 mm

VPE width

130 mm

VPE height

20 mm

Classifications

ETIM 6.0

EC002637

ETIM 8.0

EC002637

ETIM 10.0

EC002637

ECLASS 9.1

27-44-04-02

ECLASS 11.0

27-46-02-01

ECLASS 13.0

27-46-02-01

ECLASS 15.0

27-46-02-01

ETIM 7.0

EC002637

ETIM 9.0

EC002637

ECLASS 9.0

27-44-04-02

ECLASS 10.0

27-44-04-02

ECLASS 12.0

27-46-02-01

ECLASS 14.0

27-46-02-01

Environmental Product Compliance

RoHS Compliance Status

Compliant without exemption

REACH SVHC

No SVHC above 0.1 wt%

SL-SMT 3.50/17/135F 3.2SN BK BX**Weidmüller Interface GmbH & Co. KG**

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Technical data**Important note**

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Approvals

Approvals



Approvals MAMID	https://mdcop.weidmueller.com/mediadelivery/rendition/900_319262/-T1z1mm-S800/
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL BASE STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

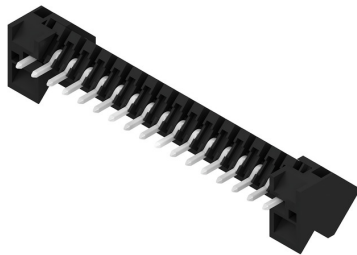
SL-SMT 3.50/17/135F 3.2SN BK BX

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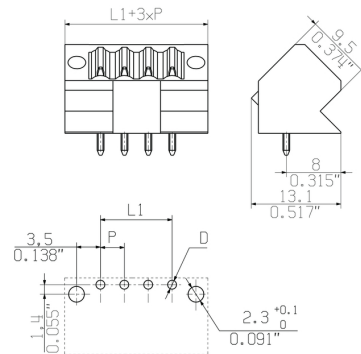
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Drawings

Product image



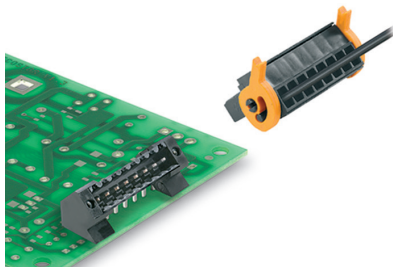
Dimensional drawing



LAYOUT FINISHED HOLES

Similar to illustration

Example of use



Rev.

Insulation material type	LCP
Insulation material colors	black
Insulation material flammability class	UL94 V-0
Insulation resistance	>0.5x10 ⁶ MOhm
Contact base material	CuSn
Contact plating (mating end)	see order sheet
Contact plating (solder end)	see order sheet

together with counterpart

Pitch P	mm/inch	3.5/0.138	
Number of rows		1	
Dielectric strength (r.m.s withstand voltage)	kV	>2.2	
Mechanical operating cycles	acc.to IEC512	25	
Plug in force (max.)	N/Pole	10	1)
Pull out force (max.)	N/Pole	10	1)
Through resistance (typical)	m Ohm	4.5	
Operating temperatur range	°C	-20..100	2)
Degree of protection acc. to VDE 0106 (plugged/unplugged)		finger safe/back of hands	
Degree of protection acc. to DIN EN 60529(plugged/unplugged)		IP20/IP10	
Solder pin length L	mm/inch	3.2/0.126	
PCB hole diameter D (wave soldering)	mm/inch	1.3+0.1/0.51+0.004	3)
PCB hole diameter D (reflow soldering)	mm/inch	n.a.	4)
Resistance to soldering heat acc. to DIN IEC 60512-6	°C/sec	-	5)
Resistance to soldering heat acc. to EN 61760-1	°C/sec	290/30	6)
Solderability classification acc. to EN 61760-1		class A	
Solder connection type		Reflow	
Solder pin diameter d (max.)	mm/inch	1.2/0.047	

Coding possibility	yes/no	yes (accessory)
Joinable without loss of pitch	yes/no	no
Manual assembly of modules	yes/no	no
Max. number of poles	n	24

Rated cross section acc. to EN 60999	mm ²	n.a.		
Rated current @ 20°C ambient (together with)	A	16.8 (BL3.5)	7)	
Rated current @ 40°C ambient (together with)	A	14.4 (BL3.5)	7)	
Overvoltage category / Pollution degree		III/3	III/2	II/2
Rated voltage	V	160	160	250
Rated impulse voltage	kV	2.5	2.5	2.5

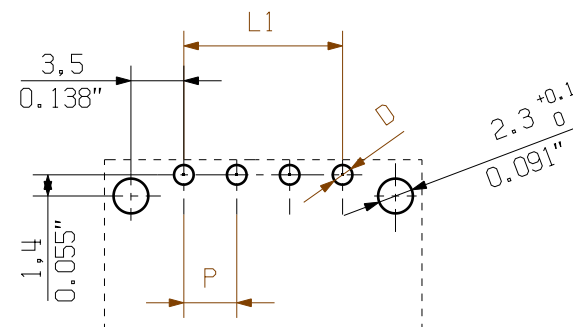
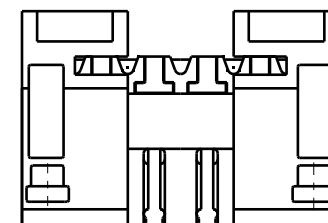
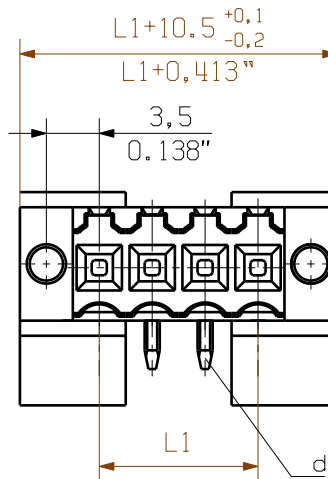
Rated voltage	V	300	-	300
Rated current	A	10	-	10
AWG wire range (field wiring / factory wiring)		n.a.		

Rated voltage	300	-	300
Rated current	10	-	10
AWG wire range (field wiring / factory wiring)	n.a.		

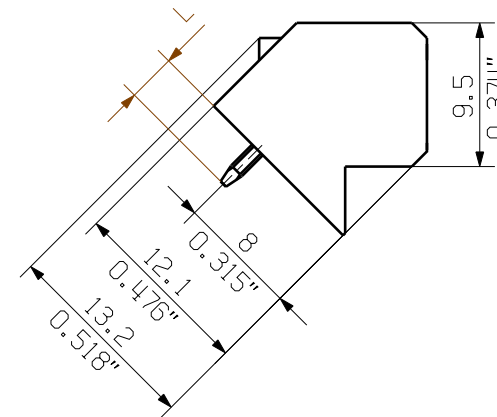
cardbox

www.weidmueller.de..

- Subject to technical changes



LAYOUT FINISHED HOLES



24	80,50	3,169
23	77,00	3,031
22	73,50	2,894
21	70,00	2,756
20	66,50	2,618
19	63,00	2,480
18	59,50	2,343
17	56,00	2,205
16	52,50	2,067
15	49,00	1,929
14	45,50	1,791
13	42,00	1,654
12	38,50	1,516
11	35,00	1,378
10	31,50	1,240
9	28,00	1,102
8	24,50	0,965
7	21,00	0,827
6	17,50	0,689
5	14,00	0,551
4	10,50	0,413
3	7,00	0,276
2	3,50	0,138
n	L1 [mm]	L1 [Inch]

STIFTLAENGE L	TOLERANZ
3,2	0,1
	-0,3

SHOWN: SL3.5/4/135F

	METRIC TOLERANCES: X. = ± 0.3 X.X = ± 0.1 X.XX = ± 0.05				CAT.NO.: .	
	39056/5 07.07.08 HELIS_MA	01			C 42538 01	
	MODIFICATION				DRAWING NO. ISSUE NO. SHEET 02 OF 03 SHEETS	
		DATE	NAME	SL SMT 3.5/./135F STIFTLEISTE PIN HEADER		
	DRAWN	04.07.2008	HELIS_MA			
	RESPONSIBLE		HERTEL_S			
	CHECKED	07.07.2008	HECKERT_M			
SCALE: 2/1	APPROVED		HECKERT_M	PRODUCT FILE: SL-SMT 3.5		
SUPERSEDES: .				7312		

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

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Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Germany

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Fax: +49 5231 14-292083

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.